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Please cancel, without prejudice, claims 1-18 in the underlying PCT application.

Please also cancel, without prejudice, revised claim 1 in the annex to the International Preliminary Examination Report.

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Please add the following new claims:

19. (New) An apparatus for sensing electromagnetic radiation, comprising:

a detector structure to sense electromagnetic radiation, the detector structure formed on a semiconductor substrate;

a protective window for the detector structure, and  
a micromechanically producible image-producing optical imaging system forming an image of a subject onto a plane of the detector structure.

20. (New) The apparatus according to claim 19, wherein the optical imaging system includes a micromechanically producible lens.

21. (New) The apparatus according to claim 19, wherein the optical imaging system is rigidly joined to the detector structure.

22. (New) The apparatus according to claim 19, wherein the detector structure includes multiple separate detector elements and the imaging system includes multiple lenses, each lens of the multiple lenses being associated with a respective one of the detector elements.

23. (New) The apparatus according to claim 19, wherein the detector structure includes multiple separate detector elements and the imaging system includes multiple lenses, wherein at

least one of the multiple lenses is provided for a group of the detector elements.

24. (New) The apparatus according to claim 19, wherein the optical imaging system forms the protective window.

25. (New) The apparatus according to claim 19, further comprising:

a protective housing, the optical imaging system being set into the protective housing.

26. (New) The apparatus according to claim 19, further comprising:

spacers provided between the substrate of the detector structure and the optical imaging system.

27. (New) The apparatus according to claim 19, wherein the detector structure includes multiple separate detector elements, the detector elements being separated from one another by optical partitions.

28. (New) The apparatus according to claim 27, wherein the optical partitions are coated to decrease transmission.

29. (New) The apparatus according to claim 19, wherein the optical imaging system is constructed on a semiconductor substrate.

30. (New) The apparatus according to claim 19, wherein the optical imaging system and the substrate of the detector structure are made of the same material.

31. (New) The apparatus according to claim 19, wherein at least one of the optical imaging system and the substrate of the detector structure is made at least partially of silicon.